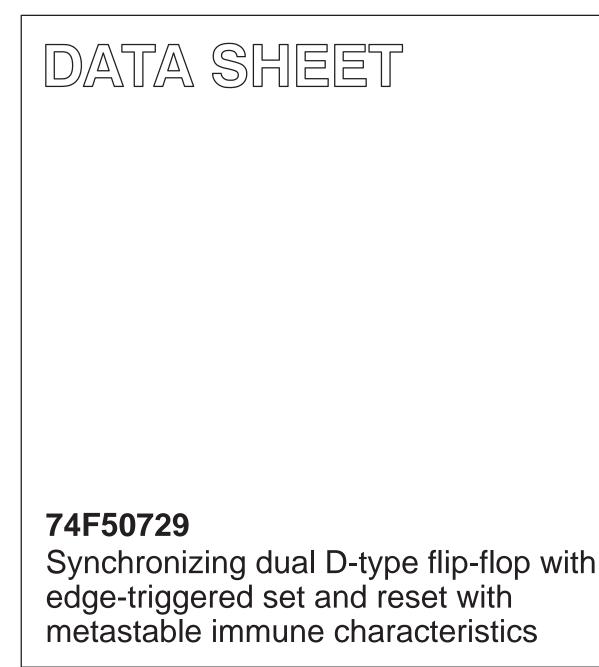
INTEGRATED CIRCUITS



Product data Supersedes data of 1990 Sep 14 2003 Jan 20



Philips Semiconductors

74F50729

FEATURES

- Metastable immune characteristics
- Output skew less than 1.5 ns
- High source current (I_{OH} = 15 mA) ideal for clock driver applications
- See 74F5074 for synchronizing dual D-type flip-flop
- See 74F50109 for synchronizing dual J-K positive edge-triggered flip-flop
- See 74F50728 for synchronizing cascaded dual D-type flip-flop
- Industrial temperature range available (-40 °C to +85 °C)

DESCRIPTION

The 74F50729 is a dual positive edge-triggered D-type featuring individual data, clock, set and reset inputs; also true and complementary outputs.

The 74F50729 is designed so that the outputs can never display a metastable state due to setup and hold time violations. If setup time and hold time are violated the propagation delays may be extended beyond the specifications but the outputs will not glitch or display a metastable state. Typical metastability parameters for the 74F50729 are: $\tau \cong 135$ ps and $\tau \cong 9.8 \times 10^6$ sec, where τ represents a function of the rate at which a latch in a metastable state resolves that condition, and T_o represents a function of the measurement of the propensity of a latch to enter a metastable state.

Set (SDn) and reset (RDn) are asynchronous positive-edge triggered inputs and operate independently of the clock (CPn) input. Data must be stable just one setup time prior to the low-to-high transition of the clock for guaranteed propagation delays.

Clock triggering occurs at a voltage level and is not directly related to the transition time of the positive-going pulse. Following the hold time interval, data at the Dn input may be changed without affecting the levels of the output.

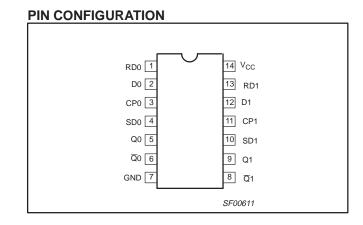
ORDERING INFORMATION

	ORDER	CODE	
DESCRIPTION	COMMERCIAL RANGE V _{CC} = 5V ±10%, T _{amb} = 0 °C to +70 °C	INDUSTRIAL RANGE V_{CC} = 5V \pm 10%, T_{amb} = –40 °C to +85 °C	PKG DWG #
14-pin plastic DIP	N74F50729N	I74F50729N	SOT27-1
14-pin plastic SO	N74F50729D	I74F50729D	SOT108-1

INPUT AND OUTPUT LOADING AND FAN OUT TABLE

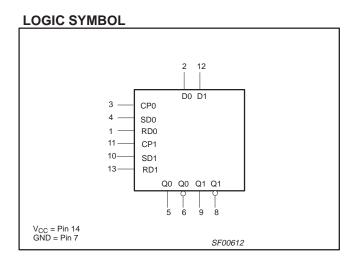
PINS	DESCRIPTION	74F (U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
D0, D1	Data inputs	1.0/0.417	20 μΑ / 250 μΑ
CP0, CP1	Clock inputs (active rising edge)	1.0/1.0	20 μΑ / 20 μΑ
SD0, SD1	Set inputs (active rising edge)	1.0/1.0	20 μΑ / 20 μΑ
RD0, RD1	Reset inputs (active rising edge)	1.0/1.0	20 μΑ / 20 μΑ
Q0, Q1, <u>Q</u> 0, <u>Q</u> 1	Data outputs	750/33	15 mA / 20 mA

NOTE: One (1.0) FAST unit load is defined as: 20 μA in the high state and 0.6 mA in the low state.



ТҮРЕ	TYPICAL f _{MAX}	TYPICAL SUPPLY CURRENT (TOTAL)
74F50729	120 MHz	19 mA

74F50729



METASTABLE IMMUNE CHARACTERISTICS

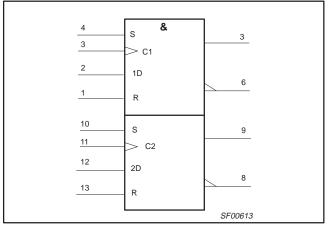
Philips Semiconductors uses the term 'metastable immune' to describe characteristics of some of the products in its family. Specifically the 74F50XXX family presently consist of 4 products which will not glitch or display metastable immune characteristics. This term means that the outputs will not glitch or display an output anomaly under any circumstances including setup and hold time violations. This claim is easily verified on the 74F5074. By running two independent signal generators (see Fig. 1) at nearly the same frequency (in this case 10 MHz clock and 10.02 MHz data) the device-under-test can be often be driven into metastable state. If the Q output is then used to trigger a digital scope set to infinite persistence the \overline{Q} output will build a waveform. An experiment was run by continuously operating the devices in the region where metastability will occur.

When the device-under-test is a 74F74 (which was not designed with metastable immune characteristics) the waveform will appear as in Fig. 2.

Figure 2 shows clearly that the \overline{Q} output can vary in time with respect to the Q trigger point. This also implies that the Q or \overline{Q} output waveshapes may be distorted. This can be verified on an analog scope with a charge plate CRT. Perhaps of even greater interest are the dots running along the 3.5V volt line in the upper right hand quadrant. These show that the \overline{Q} output did not change state even though the Q output glitched to at least 1.5 volt, the trigger point of the scope.

When the device-under-test is a metastable immune part, such as the 74F5074, the waveform will appear as in Fig. 3. The 74F5074 \overline{Q} output will appear as in Fig. 3. The 74F5074 Q output will not vary with respect to the Q trigger point even when the a part is driven into a metastable state. Any tendency towards internal metastability is resolved by Philips Semiconductors patented circuitry. If a metastable event occurs within the flop the only outward

IEC/IEEE SYMBOL



manifestation of the event will be an increased clock-to- Q/\overline{Q} propagation delay. This propagation delay is, of course, a function of the metastability characteristics of the part defined by τ and T₀.

The metastability characteristics of the 74F5074 and related part types represent state-of-the-art TTL technology.

After determining the T_0 and t of the flop, calculating the mean time between failures (MTBF) is simple. Suppose a designer wants to use the 74F50729 for synchronizing asynchronous data that is arriving at 10 MHz (as measured by a frequency counter), has a clock frequency of 50 MHz, and has decided that he would like to sample the output of the 74F50729 10 nanoseconds after the clock edge. He simply plugs his number into the equation below:

$MTBF = e^{(t'/t)} / T_o f_C f_I$

In this formula, f_C is the frequency of the clock, f_I is the average input event frequency, and t' is the time after the clock pulse that the output is sampled (t' < h, h being the normal propagation delay). In this situation the f_I will be twice the data frequency of 20 MHz because input events consist of both of low and high transitions. Multiplying f_I by f_C gives an answer of $10^{15}\,\text{Hz}^2$. From Fig. 3. it is clear that the MTBF is greater than 10^{10} seconds. Using the above formula the actual MTBF is 1.51×10^{10} seconds or about 480 years.

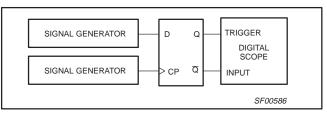
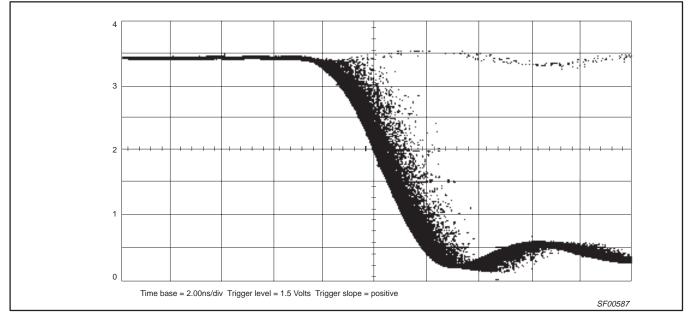
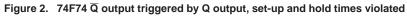


Figure 1. Test set-up

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COMPARISON OF METASTABLE IMMUNE AND NON-IMMUNE CHARACTERISTICS



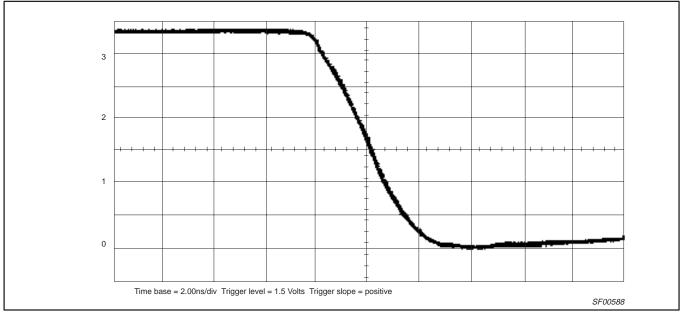
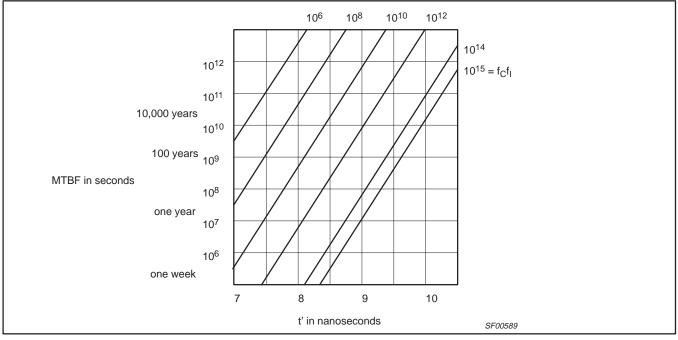


Figure 3. 74F74 \overline{Q} output triggered by Q output, set-up and hold times violated

74F50729

MEAN TIME BETWEEN FAILURES (MTBF) VERSUS t'



NOTE: V_{CC} = 5 V, T_{amb} = 25 °C, τ =135 ps, T_o = 9.8 \times 10⁶ sec

Figure 4.

TYPICAL VALUES FOR τ AND T₀ AT VARIOUS V_{CC}S AND TEMPERATURES

V _{cc}		T _{amb} = 0 °C		T _{amb} = 25 °C	T _{amb} = 70 °C		
-00	τ	T ₀	τ	T ₀	τ	T ₀	
5.5 V	125 ps	$1.0 imes 10^9 m sec$	138 ps	$5.4 imes 10^6 \ \mathrm{sec}$	160 ps	$1.7 imes 10^5 \text{sec}$	
5.0 V	115 ps	$1.3 imes 10^{10} \text{ sec}$	135 ps	$9.8 imes 10^6 m sec$	167 ps	$3.9 imes 10^4 \text{sec}$	
4.5 V	115 ps	$3.4 imes 10^{13} \text{ sec}$	132 ps	$5.1 imes 10^8 m sec$	175 ps	$7.3 imes 10^4 \text{sec}$	

FUNCTION TABLE

	INP	JTS		OUT	PUTS	OPERATING
SD	RD	СР	D	Q	Q	MODE
Ŷ	1	Х	Х	Н	L	Asynchronous set
¢	\uparrow	Х	Х	L	Н	Asynchronous reset
¢	1	\uparrow	h	Н	L	Load "1"
¢	¢	\uparrow	Ι	L	Н	Load "0"
¢	1		Х	NC	NC	Hold

NOTES:

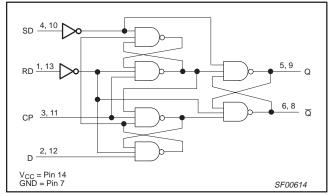
1. H = High-voltage level

2. h = High-voltage level one set-up time prior to low-to-high clock transition

3. L = Low-voltage level

- 4. I = Low-voltage level one set-up time prior to low-to-high clock transition
- 5. NC= No change from the previous set-up
- 6. X = Don't care
- 7. \uparrow = Low-to-high clock transition
- 8. \uparrow = Not low-to-high clock transition

LOGIC DIAGRAM



Product data

ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limit set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free air temperature range.)

SYMBOL	PARAMETER		RATING	UNIT
V _{CC}	Supply voltage		-0.5 to +7.0	V
V _{IH}	Input voltage		-0.5 to +7.0	V
I _{IN}	Input current		-30 to +5	mA
V _{OUT}	Voltage applied to output in high output state		–0.5 to V_{CC}	V
I _{OUT}	Current applied to output in low output state		40	mA
T _{amb}	Operating free air temperature range	Commercial range	0 to +70	°C
		Industrial range	-40 to +85	°C
T _{stg}	Storage temperature range	_	-65 to +150	°C

RECOMMENDED OPERATING CONDITIONS

				LIMITS		
SYMBOL	PARAMETER		MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage	voltage		5.0	5.5	V
V _{IH}	High-level input voltage		2.0			V
V _{IL}	Low-level input voltage				0.8	V
l _{lk}	Input clamp current				-18	mA
I _{OH}	High-level output current	V _{CC} ± 10%			-12	mA
		V _{CC} ± 5%			-15	mA
I _{OL}	Low-level output current	-			20	mA
T _{amb}	Operating free air temperature range	Commercial range	0		+70	°C
		Industrial range	-40		+85	°C

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Product data

DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

SYMBOL	PARAMET	ER	Т Т	EST			UNIT		
			CONE	MIN	TYP ²	MAX	1		
V _{OH}	High-level output voltage	•	$V_{CC} = MIN, V_{IH} = MIN$	I _{OH} = MAX	±10%V _{CC}	2.5			V
			$V_{IL} = MAX,$		±5%V _{CC}	2.7	3.4		V
				I _{OH} = -15 mA	±5%V _{CC}	2.0			V
V _{OL}	Low-level output voltage		$V_{CC} = MIN, V_{IL} = MAX,$	I _{OL} = MAX	±10%V _{CC}		0.30	0.50	V
			V _{IH} = MIN		±5%V _{CC}		0.30	0.50	V
V _{IK}	Input clamp voltage		$V_{CC} = MIN, I_I = I_{IK}$				-0.73	-1.2	V
I _I	Input current at maximur	n input voltage	$V_{CC} = MAX, V_{I} = 7.0 V$			100	μA		
I _{IH}	High-level input current		$V_{CC} = MAX, V_{I} = 2.7 V$					20	μA
IIL	Low-level input current	Dn	$V_{CC} = MAX, V_{I} = 0.5 V$					-250	μA
		CPn, SDn, RDn	1					-20	μA
I _{OS}	Short-circuit output curre	nt ³	$V_{CC} = MAX, V_{O} = 2.25 V$	1		-60		-150	mA
I _{CC}	Supply current ⁴ (total)		V _{CC} = MAX				19	27	mA

NOTES:

1. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type and function table for operating mode.

2. All typical values are at $V_{CC} = 5 \text{ V}$, $T_{amb} = 25 \text{ °C}$.

3. Not more than one output should be shorted at a time. For testing I_{OS}, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

4. Measure I_{CC} with the clock input grounded and all outputs open, then with Q and \overline{Q} outputs high in turn.

SYMBOL	PARAMETER	TEST	LIMITS									
		CONDITION	T _{amb} = +25 °C		T _{amb} = 0 °C	C to +70 °C	T _{amb} = -40 °	°C to +85 °C	1			
			v _c	V _{CC} = +5.0 V		V _{CC} = +5.0	D V \pm 10%	V _{CC} = +5.0	UNIT			
			$C_L = 50 \text{ pF},$ $R_L = 500 \Omega$			C _L = 50 pF, R _L = 500 Ω		C _L = 50 pF, R _L = 500 Ω				
			MIN	ТҮР	MAX	MIN	MAX	MIN	MAX	1		
f _{max}	Maximum clock frequency	Waveform 1	105	120		85		75		ns		
t _{PLH} t _{PHL}	Propagation delay CPn to Qn or Qn	Waveform 1	2.0 2.0	3.9 3.9	6.0 6.0	1.5 2.0	6.5 6.5	1.5 2.0	7.0 6.5	ns		
t _{PLH} t _{PHL}	Propagation delay SDn RDn_to Qn or Qn	Waveform 2	2.0 3.0	4.0 5.0	6.5 7.5	1.5 2.0	7.5 8.0	1.5 2.0	7.5 8.0	ns		
t _{ok(o)}	Output skew ^{1, 2}	Waveform 4			1.5		1.5		1.5	ns		

AC ELECTRICAL CHARACTERISTICS

NOTES:

1. | tPLH actual -tPHL actual | for any one output compared to any other output where N and M are either LH or HL.

2. Skew lines are valid only under same conditions (temperature, V_{CC}, loading, etc.).

74F50729

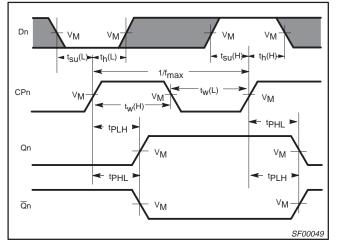
AC SETUP REQUIREMENTS

SYMBOL	PARAMETER	TEST				L	MITS			
		CONDITION	T _{an}	_{1b} = +25	°C	T _{amb} = 0 °C to +70 °C		$T_{amb} = -40 \ ^{\circ}C \text{ to } +85 \ ^{\circ}C$		
			v _c	_C = +5.0) V	V _{CC} = +5.0) V \pm 10%	V _{CC} = +5.0) V \pm 10%	UNIT
			C _L R	_ = 50 pl _ = 500	F, Ω	C _L = 5 R _L = 5	i0 pF, 500 Ω	C _L = 5 R _L = 5		
			MIN	ТҮР	MAX	MIN	MAX	MIN	MAX	
t _{su} (H) t _{su} (L)	Setup time, high or low Dn to CPn	Waveform 1	1.5 1.5			2.0 2.0		2.0 2.0		ns
t _h (H) t _h (L)	Hold time, high or low Dn to CPn	Waveform 1	1.0 1.0			1.5 1.5		1.5 1.5		ns
t _w (H) t _w (L)	CPn pulse width, high or low	Waveform 2	3.0 4.0			3.5 6.0		3.5 6.0		ns
t _w (L)	SDn, RDn pulse width, low	Waveform 3	3.5			4.0		4.0		ns
t _{rec}	Recovery time SDn, RDn to CPn	Waveform 3	6.0			6.5		6.5		ns
t _{rec}	Recovery time SDn to RDn or RDn to SDn	Waveform 3	1.0			1.0		1.0		ns

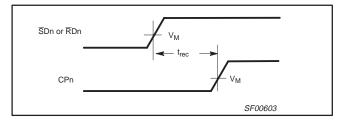
AC WAVEFORMS

For all waveforms, $V_M = 1.5$ V.

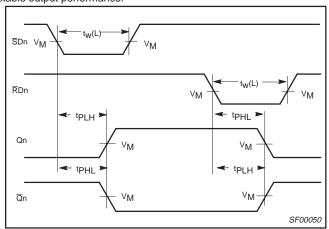
The shaded areas indicate when the input is permitted to change for predictable output performance.



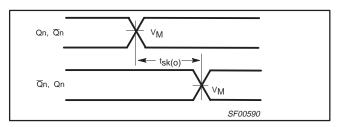
Waveform 1. Propagation delay for data to output, data set-up time and hold times, and clock width, and maximum clock frequency



Waveform 3. Recovery time for set or reset to output



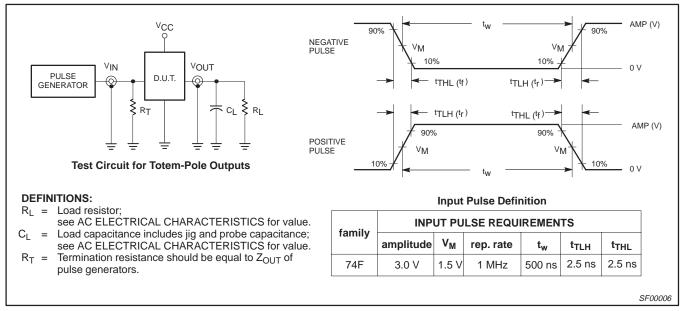
Waveform 2. Propagation delay for set and reset to output, set and reset pulse width



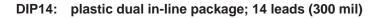
Waveform 4. Output skew

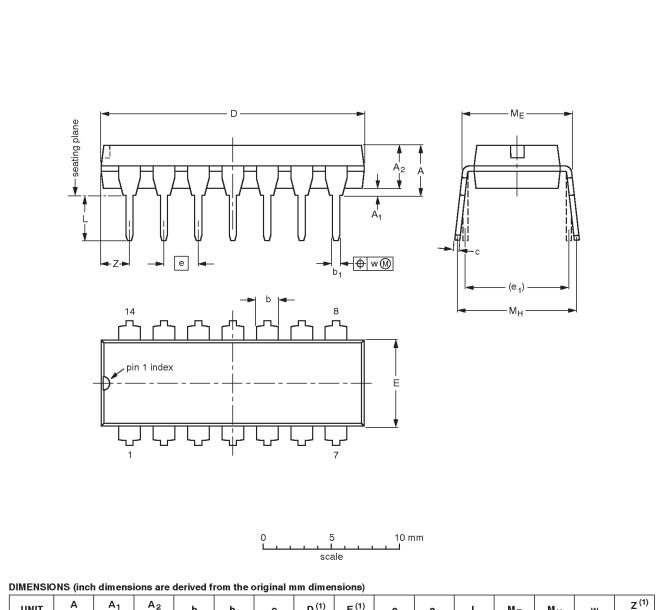
74F50729

TEST CIRCUIT AND WAVEFORMS



2003 Jan 20





UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	с	D ⁽¹⁾	E ⁽¹⁾	е	e ₁	L	М _Е	М _Н	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.13	0.53 0.38	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.2
inches	0.17	0.020	0.13	0.068 0.044	0.021 0.015	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.087

Note

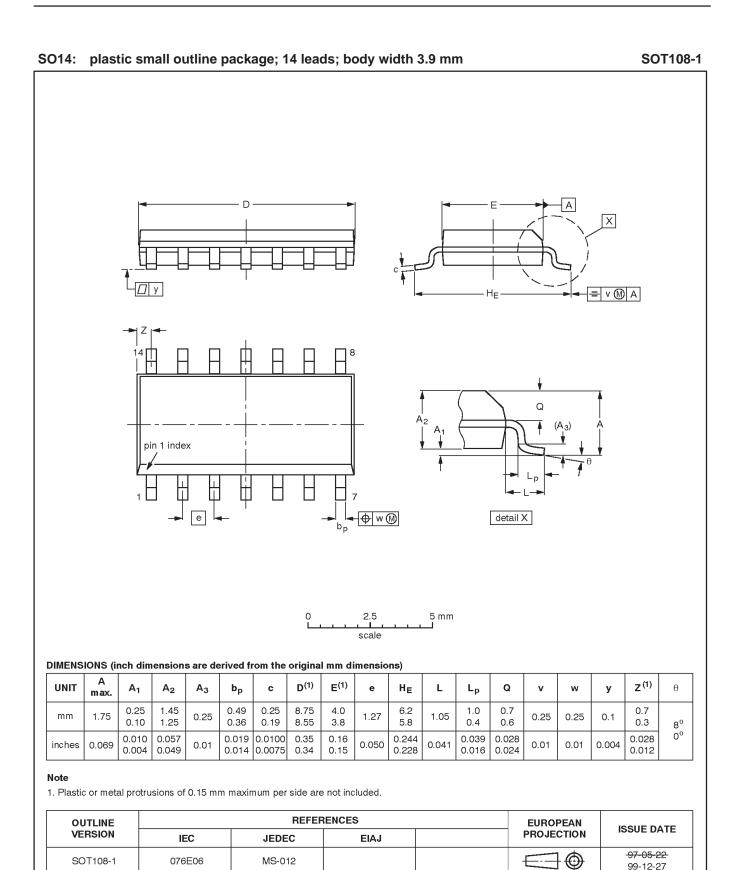
1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN				
VERSION	IEC	JEDEC	EIAJ	PROJECTION		ISSUE DATE	
SOT27-1	050G04	MO-001	SC-501-14			-95-03-11 99-12-27	

SOT27-1

74F50729

74F50729



Product data

74F50729

REVISION HISTORY

Rev	Date	Description	
_3	20030120	Product data (9397 750 10957); ECN 853-1390 29385 (date: 20030114); supersedes Product specification 74F50729_2 of 1990 Sep 14 (9397 750 05216).	
		Modifications:	
		 Page 8; AC Set-up Requirements: t_{rec}, Recovery time SDn to RDn or RDn to SDn (at T_{amb} = +25 °C) from 6.0 ns (min) to 1.0 ns (min). 	
_2	19900914	Product specification (9397 750 05216); ECN 853-1390 00420 (date: 20030114).	

Data sheet status

Level	Data sheet status ^[1]	Product status ^{[2] [3]}	Definitions
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
111	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

[1] Please consult the most recently issued data sheet before initiating or completing a design.

[2] The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.

[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

Definitions

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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Date of release: 01-03

9397 750 10957

Let's make things better.



